

HIPPO III
486

The material in this manual is for information only and is subject to change without notice.

REVISION: 1.0

IBM, IBM PC/XT/AT, PC-DOS, MS-DOS, OS/2, INTEL, AMI ARE THE TRADEMARKS OR REGISTERED TRADEMARKS OF THEIR RESPECTIVE OWNERS.

RADIO FREQUENCY INTERFERENCE STATEMENT

This equipment generates and uses radio frequency energy and if not installed and used properly, that is, in strict accordance with the manufacturer's instructions, may cause interference with radio and television reception.

If this equipment does cause interference to radio or TV reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- * Reorient the receiving antenna.*
- * Relocate the computer away from the receiver.*
- * Move the computer away from the receiver.*
- * Plug the computer into a different outlet so that computer and receiver are on different branch circuits.*
- * Ensure that card slot covers are in place when no card is installed.*
- * Ensure that card mounting screws, attachment connector screws, and ground wires are tightly secured.*
- * If peripherals are used with this system, it is suggested to use shielded, grounded cables, with in-line filters if necessary.*

If necessary, the user should consult the dealer service representative for additional suggestions.

The manufacturer is not responsible for any radio or TV interference caused by unauthorized modifications to this equipment. It is the responsibility of the user to correct such interference.

Note

1. *Electronic components are sensitive to dust and dirt. Do inspect and clean the computer system regularly.*
2. *Turn off the power whenever you install or remove any connector, memory module and add-on card. Before turning on the power, make sure that all the connectors, memory modules and add-on cards are secured.*
3. *After power is on, wait for a minute. The system BIOS are going through a self-test during this period and nothing is shown on the screen. After the self-test, the system BIOS will initialize the display adaptor and show messages.*
4. *The SIMM sockets are fragile device. Do not force the SIMM modules into the sockets. It may break the locking latches.*

Preface

The manual provides information about the installation and maintenance of OCTEK HIPPO III motherboard. In-depth explanations of the functions of this motherboard are provided. In the appendix, the system BIOS setup is explained.

The content in this manual is only for reference and is intended to provide the basic information for the general users. There are also technical information for hardware and software engineers.

In this manual, there are 4 chapters. Chapter 1 contains a brief introduction and specification of OCTEK HIPPO III motherboard. In the Chapter 2, the functions of HIPPO III are explained. It also outlines many advanced features of the CPU and the system architecture. Chapter 3 explains the installation of coprocessor, DRAM modules and jumpers. Technical information is provided in the Chapter 4.

System BIOS is described in the attached BIOS Manual. Additional information is given in the Appendix B and C for maintenance purpose.

Table of Content

Chapter 1 INTRODUCTION

Chapter 2 GENERAL FEATURES

	<i>Specification</i>	2-1
	<i>Processor</i>	2-3
	<i>Secondary Cache Memory</i>	2-8
	<i>Memory System</i>	2-
12		
	<i>8042 Emulation</i>	2-
14		
	<i>Dual Bus Design</i>	2-
15		

Chapter 3 CONFIGURING THE SYSTEM

	<i>Installing Math Coprocessor</i>	3-1
	<i>Configuration of Cache Memory</i>	3-3
	<i>Installing RAM Modules</i>	3-5
	<i>Configuration of Memory</i>	3-6
	<i>DRAM Configuration</i>	3-7
	<i>Control of System Speed</i>	3-8
	<i>Reset CMOS Setup Information</i>	3-8
	<i>System Board Jumper Setting</i>	3-9
	<i>System Board Connectors</i>	3-10

Chapter 4 **TECHNICAL INFORMATION**

<i>Memory Mapping</i>	4-1
<i>I/O Address Map</i>	4-2
<i>System Timers</i>	4-4
<i>System Interrupts</i>	4-6
<i>Direct Memory Access (DMA)</i>	4-7
<i>Real Time Clock and CMOS RAM</i>	4-8
<i>CMOS RAM Address Map</i>	4-9
<i>Real Time Clock Information</i>	4-10
<i>System Expansion Bus</i>	4-

11

Appendix A **OPERATION AND MAINTENANCE**

<i>Static Electricity</i>	A-1
<i>Keeping The System Cool</i>	A-1
<i>Cleaning The 'Golden Finger'</i>	A-2
<i>Cleaning The Motherboard</i>	A-2

Appendix B **TROUBLESHOOTING**

<i>Main Memory Error</i>	B-1
<i>Cache Memory Failure</i>	B-1
<i>Improper Setting of Wait State</i>	B-2

Appendix C **MEMORY EXPANSION CARD LAYOUT**

Appendix D **SYSTEM BOARD LAYOUT**

Chapter 1

Introduction

OCTEK HIPPO III is designed to be a powerful platform for sophisticated software available now and in the future. It contains the most powerful microprocessor 80486 which combines CPU, numeric coprocessor and internal cache memory on a single chip. Incorporated with a highly integrated chipset which consists of an advanced cache controller, OCTEK HIPPO III fully takes advantage of the power of 80486 and provides high performance, reliability and compatibility to the user.

OCTEK HIPPO III supports a large secondary cache memory with a write-back cache controller. Cache size can be 64KB or 256KB. Access to the cache memory can be carried out in the 80486 unique burst mode. Therefore HIPPO III is a perfect choice for CAD/CAM application, file server and other advanced 32-bit computing applications and operating systems. Improved design makes the memory controller more efficient. On board memory can be added up to 32MB.

Fast A20 gate and fast reset generation are incorporated to improve the performance of advanced operation system and expanded memory managers.

Compatibility and reliability are important issues. I/O channel is compatible to standard AT bus and any peripheral may be used. On board POWERGOOD generator is essential to ensure the reliability of the system and is well-designed to work with all power supplies.

Chapter 2

General Features

SPECIFICATION

Processor :

*Intel 80486DX, 80486SX or 80487SX CPU
with optional WEITEK 4167 Co-processor*

Speed :

Turbo/normal speed

I/O Slot :

*Compatible to standard AT bus
Six 16-bit slots
Eight 8-bit slots*

Secondary Cache Memory :

*64KB or 256KB Direct mapped
Write-back cache memory*

GENERAL FEATURES

Memory :

*Shadow RAM for system and video BIOS
Page mode and hidden refresh
Flexible configuration
SIMM sockets for 256KB, 1MB or 4MB modules
Maximum 64MB on board with optional memory
expansion card*

System Support Functions :

- *8-Channel DMA (Direct Memory Access)*
- *16-level interrupt*
- *3 programmable timers*
- *CMOS RAM for system configuration*
- *Real time clock with battery back-up*
- *Fast A20 gate and fast reset*

Other Features :

- *On board POWERGOOD generation*
 - *External battery connector*
-

GENERAL FEATURES

PROCESSOR

The power of HIPPO III comes from 80486. 80486 is the state-of-art microprocessor which merges many innovative features on a single chip for advanced applications and operation systems. Fabricating with the 1um process, this CPU consists of more than one million transistors. With such high density, this CPU incorporates as many as new features to make itself the most powerful microprocessor.

80486 is a 32-bit microprocessor with 32-bit external data bus and 32-bit external address bus. It not only contain a central processing unit, but also integrates a numeric processor and a four-way set associate cache memory. It is fully binary compatible with 80386 and 80387. All existing software for PC XT/AT can be used on OCTEK HIPPO III. However, due to the new internal architecture, the performance of 80486 is two to four times of 80386.

Cache memory can improve the overall performance of a computer system. Nevertheless, if the cache memory is separated from CPU, CPU still needs to fetch code and data through external bus. That means the data transfer rate should not be too fast so that the external devices are able to keep pace with the CPU. In 80486, the cache controller and cache memory are integrated into the chip. Most of the operations can be carried out inside the CPU, which reduces the bus operations on external data and address bus and thus speeds up the internal execution.

GENERAL FEATURES

GENERAL FEATURES

The cache memory is a 8K bytes, 16 bytes line size, four-way set associative configuration. The hit rate of this configuration is much better than 32K bytes two-way set associative external cache because a four-way set associative architecture provides better performance in a multitasking and multi-processor environment.

Bus snooping feature keeps the cache memory consistent with the main memory. When an external processor overwrites the content in the main memory, the corresponding data in the internal cache memory will be invalidated and will be fetched from main memory when CPU reads this data.

If a read miss occurs, the CPU will initiate a burst mode read operation. In burst mode read operation, CPU performs four successive read operations each of which takes only one cycle. Total 128 bits data are fetched into the CPU's internal cache. Since burst mode read operation is very fast, the traffic of the CPU bus is greatly reduced and the bus is available to other bus masters, such as DMA controller.

Reading 128 bits data into CPU will take some times. In order to reduce the delay, the internal cache controller works parallel with CPU. It fetches the data needed by CPU for the present operation and the CPU read cycle is terminated. Then the other data are read into the internal cache memory while CPU is doing something else. This arrangement permits the CPU to run at zero wait state.

GENERAL FEATURES

By eliminating the access to external bus, operations with the internal cache can be completed in a single cycle. 80386 at least needs two cycles for an operation. To further increase the rate of data transfer inside the CPU, the internal bus of the cache memory is increased to 128 bits, which is four times of the external bus. Since, in most of the time, the CPU is using the internal cache, the large bus size substantially improves the overall performance.

When the CPU writes data to the main memory, the data is first stored in a write buffer. There are four write buffers. When the external bus is idle, data will be sent to the main memory. If all buffers are filled, it can start write operation in burst mode. Since the internal cache is updated immediately, the CPU need not suspend its operation and there is no need to wait for the external device to update the main memory.

Many often-used instructions are executed in a clock cycle and some instructions are modified to take fewer cycles than in 80386. On the contrary, 80386 may take two to three more cycles for the same instruction. The CPU contains an advanced instruction pipeline structure and a 32-byte code queue to speed up the execution.

80486 includes all the functions of 80386 and is able to support sophisticated software and operation systems which are widely employed now. It is able to operate in real mode, protected mode and virtual 8086 mode.

GENERAL FEATURES

Internal memory management unit provides a flexible addressing scheme for the next generation operation system. Multitasking, concurrent operation and manipulating huge data base can be accomplished with excellent performance. Paging mechanism is employed to allow powerful operating system to implement virtual memory. Each segment is divided into several pages which are 4K bytes per page. Page mechanism is transparent to software and allows software to address 64 terabytes. Furthermore, the 64KB segment boundary which is an barrier of 8088 and 80286 is removed and the segment length can be increased up to 4GB.

The demand for sophisticated, number-crunching scientific and business applications has rapidly increased in recent years. In the past, microprocessor features an integer Arithmetic Logic Unit which only handles simple integer operations such as addition and multiplication. Floating-point operations which are actually utilized by applications must be accomplished through software routines.

To meet the demand of floating-point calculation, a numeric coprocessor is necessary. However, an external coprocessor has been found to be the bottleneck of data transfer. 80486 integrates the coprocessor on chip and thus the data transfer to external bus is eliminated. The on-chip coprocessor is compatible with 80387. It works parallel with other units in the CPU, which results in a better performance of numeric process.

GENERAL FEATURES

SECONDARY CACHE MEMORY

Although there is 8K bytes internal cache memory inside the CPU, a secondary cache memory is still necessary under some circumstances, such as when running multi-user or multitasking operation systems, or installing several devices with bus master capability. A direct-mapped write-back cache controller is incorporated in HIPPO III 486 and it supports up to 256KB cache memory.

In a single user system, when only DOS is used and few megabytes memory is installed, the internal cache memory is adequate and the performance is still very high.

In a multi-user or multitasking environment, CPU has to switch from one process to another, which involves a large amount of data transfer. The performance to a great extent depends on the data transfer rate. In a 80486 system, a large portion of the internal cache memory has to be updated to the main memory and then the data for another process is retrieved into the cache memory. The low speed main memory will substantially slow down the system.

In order to shorten the time required for switching between processes, a secondary cache memory is needed as a buffer between the slow speed main memory and the internal cache memory of 80486. Wait state is thus eliminated when the CPU reads external data from the secondary cache memory. Furthermore, the secondary cache memory can support the burst mode of 80486. The CPU is able to run at full speed.

Since there is already a 8K bytes cache memory in 80486, a small cache memory, such as 32K bytes, can not substantially improved the performance. On the other hand, the secondary cache should be able to contain a copy of the internal cache memory or more,

GENERAL FEATURES

which means data of different processes can coexist in the secondary cache memory. So, an optimal size is 128K or 256K bytes and this size is adequate for over 8M bytes main memory.

The secondary cache also helps to reduce the main memory bus utilization. In a system with several devices using bus master for data transfer, the main memory bus will be very bus but all the devices have to share a single memory bus. So, the less the CPU accesses the main memory, the more the external devices is able to use the memory bus.

In HIPPO III, the secondary cache controller is incorporated in the chipset. There is no need to install an external cache controller. A write-back direct-mapped scheme is implemented in HIPPO III. In a direct-mapped cache memory, the cache memory is treated as a buffer for the main memory. The main memory is logically divided into pages which has the size equal to the cache memory size. Each location in the cache memory is directly mapped into the same location in each page of main memory.

GENERAL FEATURES

Advanced features are incorporated to further improve the overall performance and to support sophisticated 32-bit software. Firstly, the cache controller is able to work in the unique 80486 burst read mode, which results in true zero wait state operation at high speed.

The write policy of the HIPPO III cache controller is write-back. In a cache-based system, the performance is downgraded when there is a lot of write operations because the CPU has to update both cache memory and main memory simultaneously. In many cache designs, the write operation is buffered, which is called 'post-write'. But it can only buffer a single write operation and wait state is still needed in case of multiple write operations. In 80486 system, since there is already a 8KB cache inside, the external bus operation will be mostly write operation.

In a write-back cache system, the amount of write operations to main memory is minimized. The CPU writes the data to the cache memory if the data on the same location is already in the cache memory. The main memory is not updated yet and the operation completes in a single cycle. So, it implies that writing to the same location need not initiate a main memory write operation. The main memory is only needed to be updated when the data from main memory has to replace the same location in the cache memory.

The advantage of the write-back scheme is that the main memory bus utilization is substantially reduced and hence the main memory bus can be available to other bus master devices in the system. It is very important for high-end computer systems in which several devices have to access the main memory for data transfer.

Two non-cacheable address ranges can be specified. It allows you to protect some partitions of program or the BIOS on the add-on cards. The video

GENERAL FEATURES

BIOS may be individually selected to be cacheable or not. The setup of the non-cacheable address ranges can be easily done in the BIOS setup.

GENERAL FEATURES

MEMORY SYSTEM

Two banks of DRAMs can be installed on board and two banks are on the memory expansion board. So 16 SIMM modules may be installed on your system and the maximum memory size is up to 64MB. 256KB, 1MB and 4MB DRAM SIMM modules are supported. The DRAM should be fast-page mode DRAM with CAS#-before-RAS# refresh capability.

The memory system provides a flexible memory configuration. Several combinations of DRAM types are allowed. The DRAM type and the memory size are automatically detected by the system BIOS. So, you may easily change the configuration of the system.

The memory controller system supports page mode. The memory is divided into pages with equal size. Successive memory accesses within the same page need not require wait state. Furthermore, a burst line fill mode is implemented. In case of a read miss of cache memory, 16 bytes data will be fetched from main memory to cache memory. Using page mode operation will speed up the line fill operation. To enhance the system performance, shadow RAM mode is supported. In shadow RAM mode, system BIOS and video BIOS contained in low speed memory such as EPROM and ROM are copied into DRAM. Improvement is significant because access to DRAM is much faster than ROM.

GENERAL FEATURES

The memory refresh logic is redesigned to improve the system performance and power consumption. In the original PC/AT design, the memory refresh operation will suspend the CPU operation because it has to access the main memory. In a high speed system like HIPPO III, the CPU indeed can process a large amount of operations in the memory refresh period.

By implementing hidden refresh method, the refresh operations for expansion card on the AT bus and for the main memory are separated. To be compatible, the refresh operation for AT bus will not be changed. But the refresh operation for main memory will be carried out individually and will be done when there is no access to main memory. Furthermore, the frequency of the main memory refresh operation may be set to 'normal' or 'slow'. All types of DRAM can be used in 'normal' mode. When 'slow' mode is selected, the availability of main memory is increased but the refresh period of DRAM should be longer. Since the refresh period of DRAM from different manufacturers may vary, consult your dealer for detail.

GENERAL FEATURES

8042 EMULATION

Now, there are many PC designs with a special feature for OS/2 optimization. It is intended to speed up the protected mode switching operation which is done by the slow speed keyboard controller in the original PC design. However, this feature often causes compatibility problem because they use different hardware logic design to bypass the keyboard controller. Thus, the BIOS is needed to be modified to take advantage of it. An application without modification may cause problem.

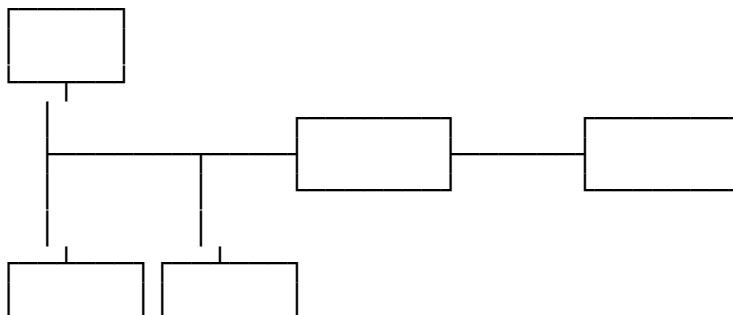
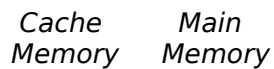
In HIPPO III, there are some logic designs in the chipset to emulate the keyboard controller. An application can work in the usual way to send commands to keyboard controller, but these commands are in fact interpreted by the chipset. The protected mode switching operation is much faster. There will be no potential problem since modification of software is not needed.

GENERAL FEATURES

DUAL BUS DESIGN

It is very important that a high speed system should be compatible with existing peripherals without lowering the performance. To be compatible, the I/O slot should run at 8MHz or slower. On the other hand, the rest of the system are running at full speed.

In HIPPO III, a dual bus design is employed. A high speed bus links the CPU, coprocessor, cache memory and main memory. This bus is synchronous with clock of the CPU and the data transfer is 32 bits. Whenever there is a request for transferring data to or from I/O slot, the chipset is responsible for handling the conversion between the bus. The clock rate of the high speed bus will not be reduced, which eliminates many compatibility problem.



GENERAL FEATURES

--	--

GENERAL FEATURES

THIS PAGE IS INTENTIONALLY LEFT BLANK

Chapter 3

Configuring The System

Important Note : Turn off the power before installing or replacing any component.

INSTALLING MATH COPROCESSOR

Math coprocessor WEITEK 4167 is a PGA devices. Beside the CPU, there is a 144-pin PGA socket. To install Math Coprocessor, be sure to line up pin 1 of the Math coprocessor with pin 1 of the socket as shown below.

CONFIGURING THE SYSTEM

Before installing the Math coprocessor, make sure that all the pins are straight. The pins are very fragile. Once these pins are bent, the coprocessor may be damaged.

The Math coprocessor is automatically detected by the system and the applications. No jumper is needed to be set.

CONFIGURING THE SYSTEM

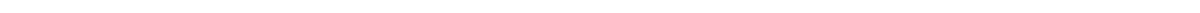
CONFIGURATION OF CACHE MEMORY

Note : if you have any question about the configuration of the cache memory, consult your local dealer. Improper configuration will cause the system malfunction.

When you install external cache memory on board, enter BIOS Setup to enable the external Cache memory. The BIOS will detect the cache memory size automatically and the size will be displayed on the screen before booting.

The external cache memory is either 64KB or 256KB. Eight pieces of SRAM should be installed on U2 to U5 and U11 to U14. JP1, JP7 and JP8 are used for setting up the cache memory. The jumper settings are ignored if cache memory disabled. The jumper settings are illustrated below :

Cache Size	JP1	JP7	JP8
64KB	2-3	2-3	2-3
256KB	1-2	1-2	1-2



CONFIGURING THE SYSTEM

For 64KB cache, use 8KX8 SRAM. For 256KB cache, use 32KX8 SRAM. A 64KX1 must be installed on U23. The IC on U21 and U22 may be installed for 64KB and 256KB cache memory

AT BUS Clock Control

JP3 is used to select the AT BUS clock after power up. Upon power up, the AT BUS clock is set to the system speed divided by 4 or 6 according to the jumper setting. The default setting is 2-3 (divided by 4).

<i>JP5</i>	<i>/6</i>	<i>/4</i>
<i>I/O Speed</i>	<i>1-2</i>	<i>2-3</i>



CONFIGURING THE SYSTEM

INSTALLING RAM MODULES

OCTEK HIPPO III has eight sockets on board for SIMM modules. Whenever you add memory to the motherboard, install four modules at the same time. Also make sure that the chips on the modules face towards the slot for memory expansion board. The modules should be locked by the sockets. Please check carefully before turning on the power. Otherwise, the system will not work properly.

To install a module, the module edge is angled into the socket's contact and then the module is pivoted into position, where the locking latches will secure it. If the module edge is not completely inserted into the socket, it cannot be pivoted to be in vertical position and should be dragged out and re-inserted again. Do not force the module into the SIMM socket. It will damage the locking latches.

The modules should be locked by the locking latches of the sockets firmly. Please check carefully before turning on the power. Otherwise, the system will not work properly.

If the BIOS reports an memory error or parity error, drag out the modules and insert them again. If the locking latches are damaged, contact your dealer to replace the socket.

CONFIGURING THE SYSTEM

CONFIGURATION OF MEMORY

The configuration of the memory is very flexible. There are several combinations of DRAM types you may consider. 256KB, 1MB or 4MB SIMM are acceptable. So, a basic system can be equipped with fewer memory and later more memory can be installed when upgrading the system. There are two banks of DRAM on the motherboard and another two banks on a memory expansion board. The memory size is detected automatically by system BIOS and indicated during memory test after reset. No jumper is needed to be set for the memory size and DRAM type.

To determine what DRAM speed rating should be used depends on the system speed and wait state. The highest performance is accomplished by using zero wait state, but high speed DRAM has to be used. If zero wait state is selected, fast page mode DRAM is needed. The wait state setting is applied to all banks of memory. Therefore make sure to install DRAM with the same speed rating, or accommodate the wait state setting to the slow DRAM type.

Because of the shadow RAM function, the 384KB memory between 640KB to 1MB can not accessed. So, the memory size found by the system BIOS is not equal to the actual memory size. For example, when there is 4MB on board, the BIOS will show 3712KB.

CONFIGURING THE SYSTEM

DRAM CONFIGURATION

Bank 0	Bank 1	Bank 2	Bank 3	Total
256K	---	---	---	1M
256K	256K	---	---	2M
1M	---	---	---	4M
256K	1M	---	---	5M
256K	256K	1M	---	6M
1M	1M	---	---	8M
256K	1M	1M	---	9M
256K	256K	1M	1M	10M
1M	1M	1M	---	12M
256K	1M	1M	1M	13M
1M	1M	1M	1M	16M
4M	---	---	---	16M
1M	4M	---	---	20M
4M	1M	---	---	20M
1M	1M	4M	---	24M
1M	4M	1M	---	24M
4M	1M	1M	---	24M
1M	1M	1M	4M	28M
1M	4M	1M	1M	28M
4M	1M	1M	1M	28M
1M	4M	---	---	32M
1M	4M	4M	---	36M
4M	1M	4M	---	36M
4M	4M	1M	---	36M
4M	1M	4M	4M	40M
1M	4M	4M	1M	40M
4M	1M	4M	1M	40M
4M	4M	1M	1M	40M

CONFIGURING THE SYSTEM

<i>4M</i>	<i>4M</i>	<i>4M</i>	<i>---</i>	<i>46M</i>
<i>1M</i>	<i>4M</i>	<i>4M</i>	<i>4M</i>	<i>52M</i>
<i>4M</i>	<i>1M</i>	<i>4M</i>	<i>4M</i>	<i>52M</i>
<i>4M</i>	<i>4M</i>	<i>4M</i>	<i>1M</i>	<i>52M</i>
<i>4M</i>	<i>4M</i>	<i>4M</i>	<i>4M</i>	<i>64M</i>

CONFIGURING THE SYSTEM

CONTROL OF SYSTEM SPEED

*System speed can be controlled by keyboard and turbo switch. To change the speed by keyboard, use '-' and '+' of the numeric keypad. Press **Ctrl** **Alt** and '-' for slow speed and press **Ctrl** **Alt** and '+' for fast speed.*

Connect P3 to the turbo switch of the case and P4 to the turbo LED of the case. When the turbo mode is selected, the turbo LED of the case will be turned on.

Whenever the system speed is set to be slow by turbo switch, it cannot be changed by the keyboard, and vice versa.

RESET CMOS SETUP INFORMATION

Sometimes, the improper setting of system setup may make the system malfunction. In this case, turn off the power and set JP10 to 1-2 for a while. The internal CMOS status register is reset. Then set the jumper to 2-3 of JP10 and turn on the power. The BIOS finds the CMOS status register is reset and regards the setup information is invalid. So it will prompt you to correct the information.

CONFIGURING THE SYSTEM

SYSTEM BOARD JUMPER SETTING

There are several options which allows user to select by hardware switches.

Display Selection

<i>JP9</i>	
<i>1-2</i>	<i>CGA, EGA, VGA</i>
<i>2-3</i>	<i>Monochrome display *</i>

CPU Type

	<i>486DX</i>	<i>486SX</i>	<i>487SX</i>
<i>JP2</i>	<i>1 - 2</i>	<i>2 - 3</i>	<i>1 - 2</i>
<i>JP3</i>	<i>1 - 2</i>	<i>2 - 3</i>	<i>1 - 2</i>
<i>JP4</i>	<i>2 - 3</i>	<i>NO</i>	<i>1 - 2</i>

Note : JP6 is reserved jumper.

CONFIGURING THE SYSTEM

SYSTEM BOARD CONNECTORS

Under typical conditions, these connectors should be connected to the indicators and switches of the system unit. The functions of connectors on the motherboard are listed below.

	<i>Description</i>
<i>P1</i>	<i>Hardware reset connector</i>
<i>P2</i>	<i>Speaker connector</i>
<i>P3</i>	<i>Turbo switch</i>
<i>P4</i>	<i>Turbo LED</i>
<i>P5</i>	<i>Power LED & Ext-lock connector</i>
<i>P6,P7</i>	<i>Power supply connector</i>
<i>P8</i>	<i>External battery connector</i>
<i>KB1</i>	<i>Keyboard connector</i>

Pin assignment of the connector are illustrated as follows:

P1 - Hardware Reset Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>Selection Pin</i>
<i>2</i>	<i>Ground</i>

CONFIGURING THE SYSTEM

P2 - Speaker Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>Data out</i>
<i>2</i>	<i>+5 Vdc</i>
<i>3</i>	<i>Ground</i>
<i>4</i>	<i>+5 Vdc</i>

P3 - Turbo Switch Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>Selection Pin</i>
<i>2</i>	<i>Ground</i>

P4 - Turbo LED Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>+5Vdc</i>
<i>2</i>	<i>LED signal</i>

CONFIGURING THE SYSTEM

P5 - Power LED & Ext-Lock Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>+5 Vdc</i>
<i>2</i>	<i>Key</i>
<i>3</i>	<i>Ground</i>
<i>4</i>	<i>Keyboard inhibit</i>
<i>5</i>	<i>Ground</i>

P6,P7 - Power Supply Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>POWERGOOD</i>
<i>2</i>	<i>+5 Vdc</i>
<i>3</i>	<i>+12 Vdc</i>
<i>4</i>	<i>-12 Vdc</i>
<i>5</i>	<i>Ground</i>
<i>6</i>	<i>Ground</i>

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>Ground</i>
<i>2</i>	<i>Ground</i>
<i>3</i>	<i>-5 Vdc</i>
<i>4</i>	<i>+5 Vdc</i>
<i>5</i>	<i>+5 Vdc</i>

CONFIGURING THE SYSTEM

6	+5 Vdc
---	--------



CONFIGURING THE SYSTEM

P8 - External Battery Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>+ Vdc</i>
<i>2</i>	<i>not used</i>
<i>3</i>	<i>Ground</i>
<i>4</i>	<i>Ground</i>

KB1 - Keyboard Connector

<i>Pin</i>	<i>Assignment</i>
<i>1</i>	<i>Keyboard clock</i>
<i>2</i>	<i>Keyboard data</i>
<i>3</i>	<i>Spare</i>
<i>4</i>	<i>Ground</i>
<i>5</i>	<i>+5 Vdc</i>

THIS PAGE IS INTENTIONALLY LEFT BLANK

Chapter 4

Technical Information

This section provides technical information about OCTEK HIPPO III and is intended for advanced users interested in the basic design and operation of OCTEK HIPPO III.

MEMORY MAPPING

<i>Address</i>	<i>Range</i>	<i>Function</i>
<i>000000-7FFFFFFF</i>	<i>000K-512K</i>	<i>System Board Memory (512K)</i>
<i>080000-09FFFF</i>	<i>512K-640K</i>	<i>System Board Memory (128K)</i>
<i>0A0000-0BFFFF</i>	<i>640K-768K</i>	<i>Display Buffer (128K)</i>
<i>0C0000-0DFFFF</i>	<i>768K-896K</i>	<i>Adaptor ROM / Shadow RAM (128K)</i>
<i>0E0000-0EFFFF</i>	<i>896K-960K</i>	<i>System ROM / Shadow RAM (64K)</i>
<i>0F0000-0FFFFFFF</i>	<i>960K-1024K</i>	<i>System BIOS ROM / Shadow RAM (64K)</i>
<i>100000-7FFFFFFF</i>	<i>1024K-8192K</i>	<i>System Memory</i>
<i>800000-FFFFFFF</i>	<i>8192K-16318K</i>	<i>System Memory</i>

TECHNICAL INFORMATION

I/O ADDRESS MAP

I/O Address Map on System Board

I/O address hex 000 to 0FF are reserved for the system board I/O.

<i>ADDRESS (HEX)</i>	<i>DEVICE</i>
<i>000-01F</i>	<i>DMA Controller 1, 8237</i>
<i>020-03F</i>	<i>Interrupt Controller 1, 8259, Master</i>
<i>040-05F</i>	<i>Timer, 8254</i>
<i>060-06F</i>	<i>Keyboard Controller</i>
<i>070-07F</i>	<i>Real Time Clock, NMI (non-maskable interrupt) mask</i>
<i>080-09F</i>	<i>DMA Page Register, 74LS612</i>
<i>0A0-0BF</i>	<i>Interrupt Controller 2, 8259</i>
<i>0C0-0DF</i>	<i>DMA Controller 2, 8237</i>
<i>0F0</i>	<i>Clear Math Coprocessor Busy</i>
<i>0F1</i>	<i>Reset Math Coprocessor</i>
<i>0F8-0FF</i>	<i>Math Coprocessor Port</i>

TECHNICAL INFORMATION

I/O address hex 100 to 3FF are available on the I/O channel.

<i>ADDRESS (HEX)</i>	<i>DEVICE</i>
<i>1F0-1F8</i>	<i>Fixed Disk</i>
<i>200-207</i>	<i>Game I/O</i>
<i>278-27F</i>	<i>Parallel Printer Port 2</i>
<i>2F8-2FF</i>	<i>Serial Port 2</i>
<i>300-31F</i>	<i>Prototype Card</i>
<i>360-36F</i>	<i>Reserved</i>
<i>378-37F</i>	<i>Parallel Printer Port 1</i>
<i>380-38F</i>	<i>SDLC, bisynchronous 2</i>
<i>3A0-3AF</i>	<i>Bisynchronous 1</i>
<i>3B0-3BF</i>	<i>Monochrome Display and Printer Adapter</i>
<i>3C0-3CF</i>	<i>Reserved</i>
<i>3D0-3DF</i>	<i>Color Graphics Monitor Adapter</i>
<i>3F0-3F7</i>	<i>Diskette Controller</i>
<i>3F8-3FF</i>	<i>Serial Port 1</i>

TECHNICAL INFORMATION

SYSTEM TIMERS

OCTEK HIPPO III has three programmable timer/counters controlled by 82C206 and they are defined as channels 0 through 2:

<i>Channel 0</i>	<i>System Timer</i>
<i>Gate 0</i>	<i>Tied on</i>
<i>Clk in 0</i>	<i>1.190 Mhz OSC</i>
<i>Clk out 0</i>	<i>8259 IRQ 0</i>

<i>Channel 1</i>	<i>Refresh Request Generator</i>
<i>Gate 1</i>	<i>Tied on</i>
<i>Clk in 1</i>	<i>1.190 Mhz OSC</i>
<i>Clk out 1</i>	<i>Request Refresh Cycle</i>

TECHNICAL INFORMATION

<i>Channel 2</i>	<i>Tone Generation of Speaker</i>
<i>Gate 2</i>	<i>Controlled by bit 0 of port hex 61 PPI bit</i>
<i>Clk in 2</i>	<i>1.190 Mhz OSC</i>
<i>Clk out 2</i>	<i>Used to drive the speaker</i>

Note: Channel 1 is programmed to generate a 15-micro-second period signal.

The 8254 Timer/Counters are treated by system programs as an arrangement of four programmable external I/O ports. Three are treated as counters and the fourth is a control register for mode programming.

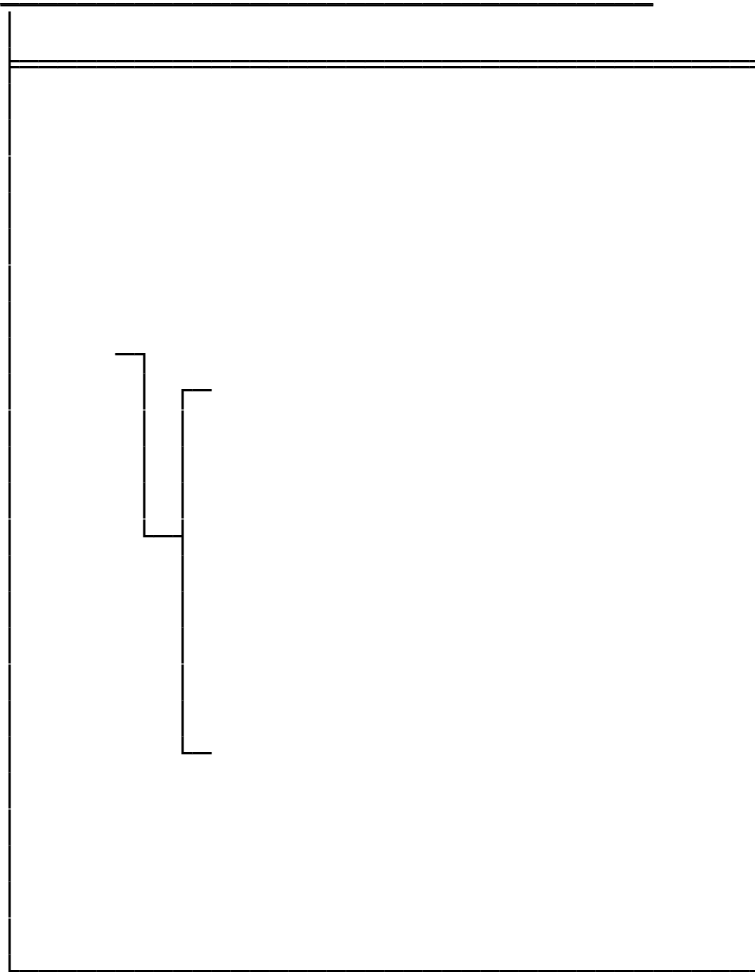
TECHNICAL INFORMATION

SYSTEM INTERRUPTS

Sixteen levels of system interrupts are provided on OCTEK HIPPO III. The following shows the interrupt-level assignments in decreasing priority.

Level		Function
<i>Microprocessor NMI</i>		<i>Parity or I/O Channel Check</i>
<i>Interrupt Controllers</i>		
<i>CTLR 1</i>	<i>CTLR 2</i>	
<i>IRQ0</i>		<i>Timer Output 0</i>
<i>IRQ1</i>		<i>Keyboard (Output Buffer Full)</i>
<i>IRQ2</i>		<i>Interrupt from CTLR 2</i>
	<i>IRQ8</i>	<i>Real-time Clock Interrupt</i>
	<i>IRQ9</i>	<i>Software Redirected to INT 0AH (IRQ2)</i>
	<i>IRQ10</i>	<i>Reserved</i>
	<i>IRQ11</i>	<i>Reserved</i>
	<i>IRQ12</i>	<i>Reserved</i>
	<i>IRQ13</i>	<i>Coprocessor</i>
	<i>IRQ14</i>	<i>Fixed Disk Controller</i>
	<i>IRQ15</i>	<i>Reserved</i>
<i>IRQ3</i>		<i>Serial Port 2</i>
<i>IRQ4</i>		<i>Serial Port 1</i>
<i>IRQ5</i>		<i>Parallel Port 2</i>
<i>IRQ6</i>		<i>Diskette Controller</i>
<i>IRQ7</i>		<i>Parallel Port 1</i>

TECHNICAL INFORMATION



TECHNICAL INFORMATION

DIRECT MEMORY ACCESS (DMA)

OCTEK HIPPO III supports seven DMA channels.

<i>Channel</i>	<i>Function</i>
<i>0</i>	<i>Spare (8 bit transfer)</i>
<i>1</i>	<i>SDLC (8 bit transfer)</i>
<i>2</i>	<i>Floppy Disk (8 bit transfer)</i>
<i>3</i>	<i>Spare (8 bit transfer)</i>
<i>4</i>	<i>Cascade for DMA Controller 1</i>
<i>5</i>	<i>Spare (16 bit transfer)</i>
<i>6</i>	<i>Spare (16 bit transfer)</i>
<i>7</i>	<i>Spare (16 bit transfer)</i>

TECHNICAL INFORMATION

The following shows the addresses for the page register.

<i>Page Register</i>	<i>I/O Address (HEX)</i>
<i>DMA Channel 0</i>	<i>0087</i>
<i>DMA Channel 1</i>	<i>0083</i>
<i>DMA Channel 2</i>	<i>0081</i>
<i>DMA Channel 3</i>	<i>0082</i>
<i>DMA Channel 5</i>	<i>008B</i>
<i>DMA Channel 6</i>	<i>0089</i>
<i>DMA Channel 7</i>	<i>008A</i>
<i>Refresh</i>	<i>008F</i>

REAL TIME CLOCK AND CMOS RAM

Real time clock and CMOS RAM are contained on board. Real time clock provides the system date and time. CMOS RAM stores system information. Both are backed up by battery and will not lose information after power off. The following page shows the CMOS RAM Address Map.

TECHNICAL INFORMATION

CMOS RAM ADDRESS MAP

<i>Addresses</i>	<i>Description</i>
<i>00-0D</i>	<i>* Real-time clock information</i>
<i>0E</i>	<i>* Diagnostic status byte</i>
<i>0F</i>	<i>* Shutdown status byte</i>
<i>10</i>	<i>Diskette drive type byte - drives A and B</i>
<i>11</i>	<i>Reserved</i>
<i>12</i>	<i>Fixed disk type byte - drives C and D</i>
<i>13</i>	<i>Reserved</i>
<i>14</i>	<i>Equipment byte</i>
<i>15</i>	<i>Low base memory byte</i>
<i>16</i>	<i>High base memory byte</i>
<i>17</i>	<i>Low expansion memory byte</i>
<i>18</i>	<i>High expansion memory byte</i>
<i>19-2D</i>	<i>Reserved</i>
<i>2E-2F</i>	<i>2-byte CMOS checksum</i>
<i>30</i>	<i>* Low expansion memory byte</i>
<i>31</i>	<i>* High expansion memory byte</i>
<i>32</i>	<i>* Date century byte</i>
<i>33</i>	<i>* Information flags (set during power on)</i>
<i>34-3F</i>	<i>Reserved</i>

REAL TIME CLOCK INFORMATION

The following table describes real-time clock

TECHNICAL INFORMATION

bytes and specifies their addresses.

<i>Byte</i>	<i>Function</i>	<i>Address</i>
<i>0</i>	<i>Seconds</i>	<i>00</i>
<i>1</i>	<i>Second alarm</i>	<i>01</i>
<i>2</i>	<i>Minutes</i>	<i>02</i>
<i>3</i>	<i>Minute alarm</i>	<i>03</i>
<i>4</i>	<i>Hours</i>	<i>04</i>
<i>5</i>	<i>Hour alarm</i>	<i>05</i>
<i>6</i>	<i>Day of week</i>	<i>06</i>
<i>7</i>	<i>Date of month</i>	<i>07</i>
<i>8</i>	<i>Month</i>	<i>08</i>
<i>9</i>	<i>Year</i>	<i>09</i>
<i>10</i>	<i>Status Register A</i>	<i>0A</i>
<i>11</i>	<i>Status Register B</i>	<i>0B</i>
<i>12</i>	<i>Status Register C</i>	<i>0C</i>
<i>13</i>	<i>Status Register D</i>	<i>0D</i>

TECHNICAL INFORMATION

SYSTEM EXPANSION BUS

OCTEK HIPPO III provides eight 16-bit slots.

The I/O channel supports:

- * *I/O address space from hex 100 to hex 3FF*
 - * *Selection of data access (either 8 or 16 bit)*
 - * *24 bit memory addresses (16MB)*
 - * *Interrupts*
 - * *DMA channels*
 - * *Memory refresh signal*
-

TECHNICAL INFORMATION

The following figure shows the pin numbering for I/O channel connectors (A-side and B-side).

TECHNICAL INFORMATION

The following figure shows the pin numbering for I/O channel connectors (C-side and D-side).

TECHNICAL INFORMATION

The following tables summarize pin assignments for the I/O channel connectors.

I/O Channel (A-Side)

<i>I/O Pin</i>	<i>Signal Name</i>	<i>I/O</i>
A1	-I/O CH CK	I
A2	SD7	I/O
A3	SD6	I/O
A4	SD5	I/O
A5	SD4	I/O
A6	SD3	I/O
A7	SD2	I/O
A8	SD1	I/O
A9	SD0	I/O
A10	-I/O CH RDY	I
A11	AEN	O
A12	SA19	I/O
A13	SA18	I/O
A14	SA17	I/O
A15	SA16	I/O
A16	SA15	I/O
A17	SA14	I/O
A18	SA13	I/O
A19	SA12	I/O
A20	SA11	I/O
A21	SA10	I/O
A22	SA9	I/O
A23	SA8	I/O
A24	SA7	I/O
A25	SA6	I/O

TECHNICAL INFORMATION

A26	SA5	I/O
A27	SA4	I/O
A28	SA3	I/O
A29	SA2	I/O
A30	SA1	I/O
A31	SA0	I/O

TECHNICAL INFORMATION

I/O Channel (B-Side)

<i>I/O Pin</i>	<i>Signal Name</i>	<i>I/O</i>
B1	GND	Ground
B2	RESET DRV	I
B3	+5 Vdc	Power
B4	IRQ9	I
B5	-5 Vdc	Power
B6	DRQ2	I
B7	-12 Vdc	Power
B8	OWS	I
B9	+12 Vdc	Power
B10	GND	Ground
B11	-SMEMW	O
B12	-SMEMR	O
B13	-IOW	I/O
B14	-IOR	I/O
B15	-DACK3	I
B16	DRQ3	O
B17	-DACK1	I
B18	DRQ1	O
B19	-Refresh	I/O
B20	CLK	O
B21	IRQ7	I
B22	IRQ6	I
B23	IRQ5	I
B24	IRQ4	I
B25	IRQ3	I
B26	-DACK2	O
B27	T/C	O
B28	BALE	O
B29	+5 Vdc	Power

TECHNICAL INFORMATION

<i>B30</i>	<i>OSC</i>	<i>O</i>
<i>B31</i>	<i>GND</i>	<i>Ground</i>

TECHNICAL INFORMATION

I/O Channel (C-Side)

<i>I/O Pin</i>	<i>Signal Name</i>	<i>I/O</i>
<i>C1</i>	<i>SBHE</i>	<i>I/O</i>
<i>C2</i>	<i>LA23</i>	<i>I/O</i>
<i>C3</i>	<i>LA22</i>	<i>I/O</i>
<i>C4</i>	<i>LA21</i>	<i>I/O</i>
<i>C5</i>	<i>LA20</i>	<i>I/O</i>
<i>C6</i>	<i>LA19</i>	<i>I/O</i>
<i>C7</i>	<i>LA18</i>	<i>I/O</i>
<i>C8</i>	<i>LA17</i>	<i>I/O</i>
<i>C9</i>	<i>-MEMR</i>	<i>I/O</i>
<i>C10</i>	<i>-MEMW</i>	<i>I/O</i>
<i>C11</i>	<i>SD8</i>	<i>I/O</i>
<i>C12</i>	<i>SD9</i>	<i>I/O</i>
<i>C13</i>	<i>SD10</i>	<i>I/O</i>
<i>C14</i>	<i>SD11</i>	<i>I/O</i>
<i>C15</i>	<i>SD12</i>	<i>I/O</i>
<i>C16</i>	<i>SD13</i>	<i>I/O</i>
<i>C17</i>	<i>SD14</i>	<i>I/O</i>
<i>C18</i>	<i>SD15</i>	<i>I/O</i>

TECHNICAL INFORMATION

I/O Channel (D-Side)

<i>I/O Pin</i>	<i>Signal Name</i>	<i>I/O</i>
<i>D1</i>	<i>-MEM CS16</i>	<i>I</i>
<i>D2</i>	<i>-I/O CS16</i>	<i>I</i>
<i>D3</i>	<i>IRQ10</i>	<i>I</i>
<i>D4</i>	<i>IRQ11</i>	<i>I</i>
<i>D5</i>	<i>IRQ12</i>	<i>I</i>
<i>D6</i>	<i>IRQ15</i>	<i>I</i>
<i>D7</i>	<i>IRQ14</i>	<i>I</i>
<i>D8</i>	<i>-DACK0</i>	<i>O</i>
<i>D9</i>	<i>DRQ0</i>	<i>I</i>
<i>D10</i>	<i>-DACK5</i>	<i>O</i>
<i>D11</i>	<i>DRQ5</i>	<i>I</i>
<i>D12</i>	<i>-DACK6</i>	<i>O</i>
<i>D13</i>	<i>DRQ6</i>	<i>I</i>
<i>D14</i>	<i>-DACK7</i>	<i>O</i>
<i>D15</i>	<i>DRQ7</i>	<i>I</i>
<i>D16</i>	<i>+5 Vdc</i>	<i>Power</i>
<i>D17</i>	<i>-MASTER</i>	<i>I</i>
<i>D18</i>	<i>GND</i>	<i>Ground</i>

TECHNICAL INFORMATION

THIS PAGE IS INTENTIONALLY LEFT BLANK

Appendix A

Operation and Maintenance

STATIC ELECTRICITY

When installing or removing any add-on card, DRAM module or coprocessor, you should discharge the static electricity on your body. Static electricity is dangerous to electronic device and can build-up on your body. When you touch the add-on card or motherboard, it is likely to damage the device. To discharge the static electricity, touch the metal of your computer. When handling the add-on card, don't contact the components on the cards or their "golden finger". Hold the cards by their edges.

KEEPING THE SYSTEM COOL

The motherboard contains many high-speed components and they will generate heat during operation. Other add-on cards and hard disk drive can also produce a lot of heat. The temperature inside the computer system may be very high. In order to keep the system running stably, the temperature must be kept at a low level. A easy way to do this is to keep the cool air circulating inside the case. The power supply contains a fan to blow air out of the case. If you find that the temperature is still very high, it would be better to install another fan inside the case. Using a larger case is recommended if there are a number of add-on cards and disk drives in the system.

CLEANING THE "GOLDEN FINGER"

Whenever inserting an add-on card to the motherboard, make sure that there is no dirt on the "golden finger" of the add-on card. If not, the contact between the "golden finger" and the slot may be poor and thus the add-on card may not work properly. Use a pencil eraser to clean the "golden finger" if dirt is found.

CLEANING THE MOTHERBOARD

The computer system should be kept clean. Dust and dirt is harmful to electronic devices. To prevent dust from accumulating on the mother-board, installing all mounting plates on the rear of the case. Regularly examine your system, and if necessary, vacuum the interior of the system with a miniature vacuum.

Appendix B

Troubleshooting

MAIN MEMORY ERROR

After power up, the monitor remains blank, and there are beep sounds indicating a main memory failure. In this case, turn off the power and remove all SIMM modules. Carefully place the modules back to the sockets and make sure that all the modules are locked by the locking latches firmly.

In some other cases, the total memory found by the BIOS is different from the actual amount of memory on board. (Note that 128K bytes memory is reserved for the shadow RAM function and will not be counted by the BIOS). It is also a memory failure and you can follow the instruction above.

CACHE MEMORY FAILURE

If the system hangs after memory test, it is likely that the cache memory has some problems when the secondary cache memory card is installed. Maybe some of the SRAMs are damaged or the contact of the IC pins is poor. Try to press the SRAM to make sure that the SRAMs are inserted in the sockets, or examine the SRAM to see whether any pins are bent under or out. If the bent pins are found, remove the SRAM, straighten the pin and place the SRAM again. You may also check the BIOS setup of the cache configuration. If the cache controller is enabled, you should select chipset's cache controller. Otherwise, the system will fail.

IMPROPER SETTING OF WAIT STATE

If the system hangs after memory test, another possible cause is the improper setting of the wait state for memory operation. The number of wait state must match the speed of the DRAM. Reset the CMOS RAM and set up the wait state. Try to increase the number of wait state.

Appendix C

Memory Expansion Card

Layout

Summary of Jumper Setting

Cache Size	JP1	JP7	JP8
64KB	2-3	2-3	2-3
256KB	1-2	1-2	1-2

	486DX	486SX	487SX
JP2	1 - 2	2 - 3	1 - 2
JP3	1 - 2	2 - 3	1 - 2
JP4	2 - 3	NO	1 - 2

JP5	/6	/4
I/O Speed	1-2	2-3

Reserved	
JP6	1-2

JP9	
1-2	CGA, EGA, VGA
2-3	Monochrome display *

Reset Setup	Reset	Normal
JP10	1-2	2-3

Appendix D

System Board Layout
